



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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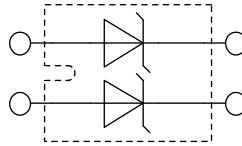


Schottky Diode

High Performance Schottky Diode
Low Loss and Soft Recovery
Parallel legs

Part number

DSS2x101-02A



Backside: isolated

E72873

Features / Advantages:

- Very low V_f
- Extremely low switching losses
- low I_{rm} values
- Improved thermal behaviour
- High reliability circuit operation
- Low voltage peaks for reduced protection circuits
- Low noise switching

Applications:

- Rectifiers in switch mode power supplies (SMPS)
- Free wheeling diode in low voltage converters

Package:

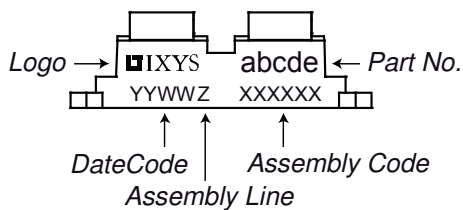
- Housing: SOT-227B (minibloc)
- Industry standard outline
- Cu base plate internal DCB isolated
- Isolation Voltage 3000 V
- Epoxy meets UL 94V-0
- RoHS compliant

Ratings

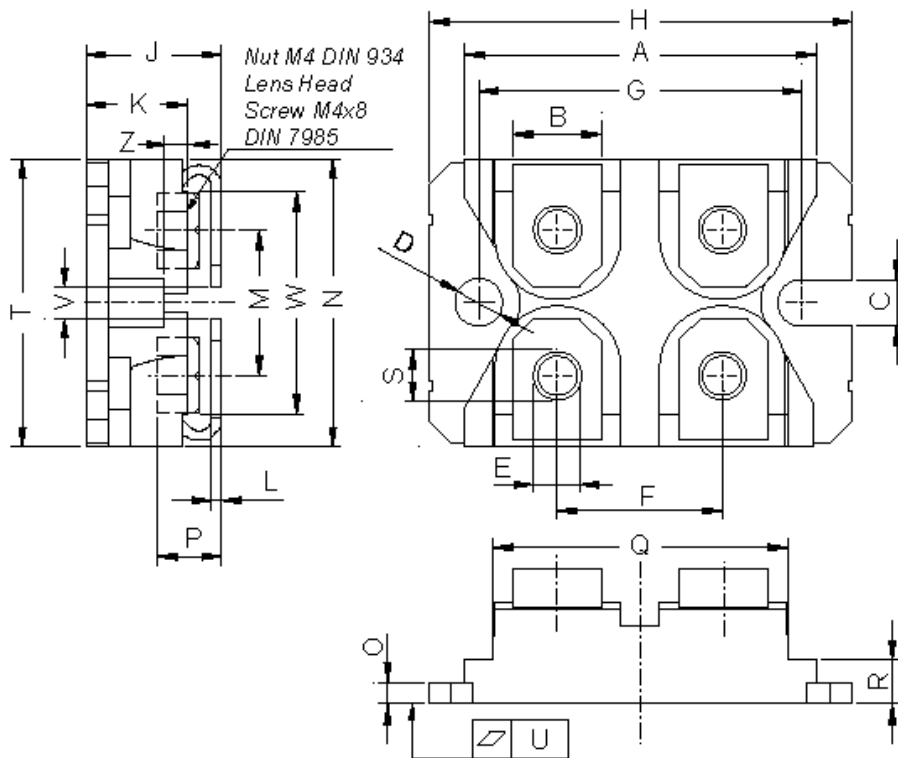
Symbol	Definition	Conditions	Ratings			Unit
			min.	typ.	max.	
V_{RRM}	<i>max. repetitive reverse voltage</i>				200	V
I_R	<i>reverse current</i>	$V_R = 200\text{ V}$			4	mA
		$V_R = 200\text{ V}$			10	mA
V_F	<i>forward voltage</i>	$I_F = 100\text{ A}$			0.94	V
		$I_F = 200\text{ A}$			1.16	V
		$I_F = 100\text{ A}$			0.84	V
		$I_F = 200\text{ A}$			1.11	V
I_{FAV}	<i>average forward current</i>	rectangular d = 0.5			100	A
V_{F0}	<i>threshold voltage</i>				0.54	V
r_F	<i>slope resistance</i>					
R_{thJC}	<i>thermal resistance junction to case</i>				0.40	K/W
T_{VJ}	<i>virtual junction temperature</i>		-40		150	°C
P_{tot}	<i>total power dissipation</i>				310	W
I_{FSM}	<i>max. forward surge current</i>	t = 10 ms (50 Hz), sine			1400	A
C_J	<i>junction capacitance</i>	$V_R = 24\text{ V}; f = 1\text{ MHz}$		787		pF

Symbol	Definition	Conditions	Ratings			Unit
			min.	typ.	max.	
I_{RMS}	RMS current	per terminal			150	A
R_{thCH}	thermal resistance case to heatsink			0.10		K/W
T_{stg}	storage temperature		-40		150	°C
Weight				30		g
M_D	mounting torque		1.1		1.5	Nm
M_T	terminal torque		1.1		1.5	Nm
V_{ISOL}	isolation voltage	t = 1 second	3000			V
		t = 1 minute	2500			V
$d_{Spp/App}$	creepage / striking distance on surface / through air	terminal to terminal	10.5	3.2		mm
$d_{Spb/Apb}$	creepage / striking distance on surface / through air	terminal to backside	8.6	6.8		mm

Product Marking



Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Code Key
Standard	DSS2x101-02A	DSS2x101-02A	Tube	10	500867

Outlines SOT-227B (minibloc)


Dim.	Millimeter		Inches	
	min	max	min	max
A	31.50	31.88	1.240	1.255
B	7.80	8.20	0.307	0.323
C	4.09	4.29	0.161	0.169
D	4.09	4.29	0.161	0.169
E	4.09	4.29	0.161	0.169
F	14.91	15.11	0.587	0.595
G	30.12	30.30	1.186	1.193
H	37.80	38.23	1.488	1.505
J	11.68	12.22	0.460	0.481
K	8.92	9.60	0.351	0.378
L	0.74	0.84	0.029	0.033
M	12.50	13.10	0.492	0.516
N	25.15	25.42	0.990	1.001
O	1.95	2.13	0.077	0.084
P	4.95	6.20	0.195	0.244
Q	26.54	26.90	1.045	1.059
R	3.94	4.42	0.155	0.167
S	4.55	4.85	0.179	0.191
T	24.59	25.25	0.968	0.994
U	-0.05	0.10	-0.002	0.004
V	3.20	5.50	0.126	0.217
W	19.81	21.08	0.780	0.830
Z	2.50	2.70	0.098	0.106

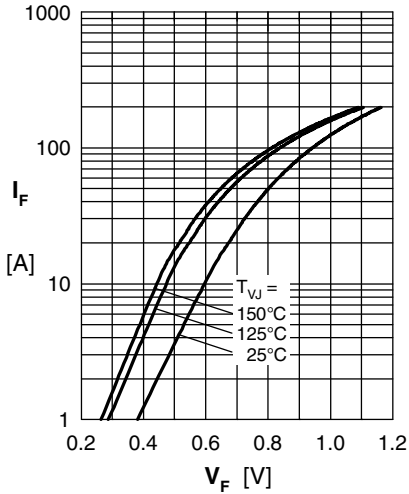


Fig. 1 Maximum forward voltage drop characteristics

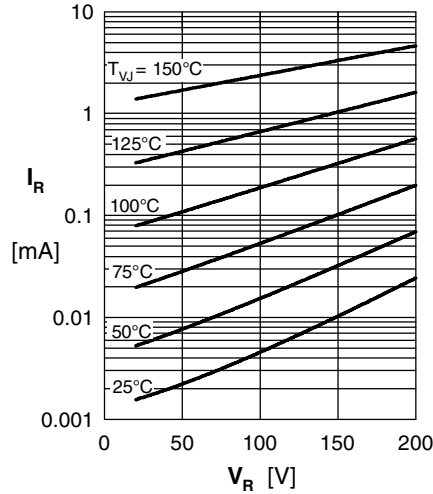


Fig. 2 Typ. reverse current I_R vs. reverse voltage V_R

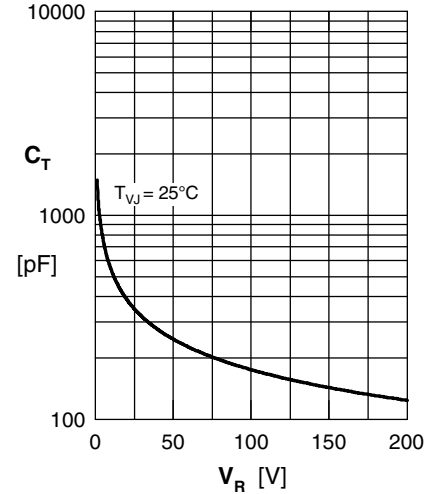


Fig. 3 Typ. junction capacitance C_T vs. reverse voltage V_R

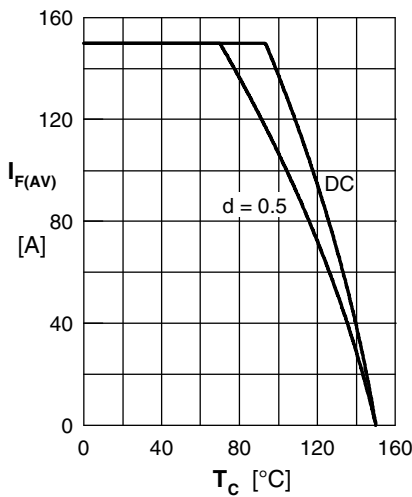


Fig. 4 Average forward current $I_{F(AV)}$ vs. case temperature T_c

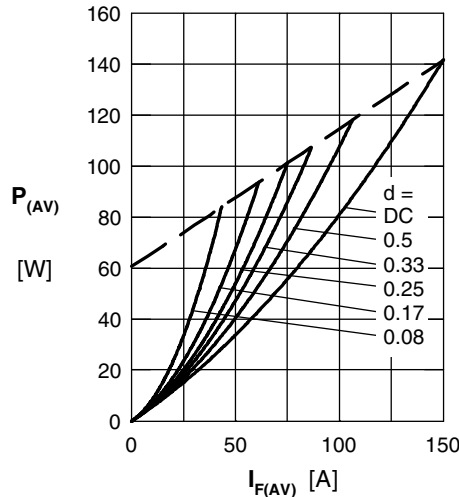


Fig. 5 Forward power loss characteristics

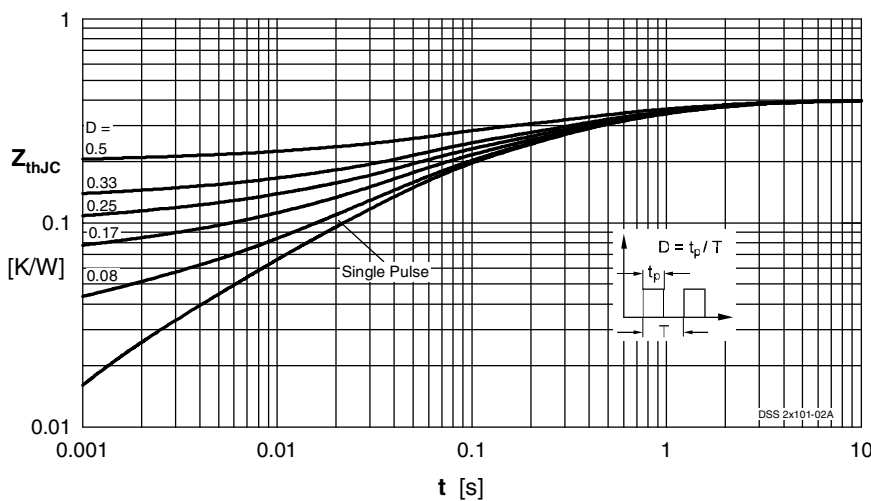


Fig. 6 Transient thermal impedance junction to case at various duty cycles

Note: All curves are per diode